

APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-35°C TO +85°C (NOTE 1)	STORAGE TEMPERATURE RANGE	-10°C TO +60°C (NOTE3)	
	OPERATING HUMIDITY RANGE	20 % TO 80 % (NOTE 2)	STORAGE HUMIDITY RANGE	20 % TO 70 % (NOTE3)	
	VOLTAGE	150 V AC (DC)	CURRENT	1 A	
	APPLICABLE CONNECTOR	DF13-10S-1. 25C	APPLICABLE CONTACT	DF13-2630SCFA (**) DF13-3032SCFA (**)	
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	X X
MARKING		CONFIRMED VISUALLY.			X X
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 m A (DC OR 1000 Hz).		30 mΩ MAX.	X —
INSULATION RESISTANCE		100 V DC.		500 MΩ MIN.	X —
VOLTAGE PROOF		500 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	X —
MECHANICAL CHARACTERISTICS					
MECHANICAL OPERATION		50 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X —
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X —
SHOCK		490 m/s <sup>2</sup> DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			X —
ENVIRONMENTAL CHARACTERISTICS					
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55→ 5 TO 35→+85→ 5 TO 35 °C TIME 30→ 10 TO 15→30→ 10 TO 15 min. UNDER 5 CYCLES.		① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X —
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			X —
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING «REFLOW AREA» 250°C MAX 10 sec MAX 230°C MIN 60 sec MAX «PREHEATING AREA» 170°C TO 190°C 60 sec TO 120 sec PUT THROUGH IN REFLOW FURNACE TWICE, LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350±10°C, SOLDERING TIME : 5sec. NO STRENGTH ON CONTACT.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X —
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE, 230±5°C FOR INSERTION DURATION, 3sec.		SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSSED.	X —
REMARKS					
NOTE1: INCLUDE THE TEMPERATURE RISING BY CURRENT					
NOTE2:NO CONDENSING					
NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD , OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION.					
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△					
Unless otherwise specifid , refer to IEC 60512.			APPROVED	KI. AKIYAMA	16.01.21
			CHECKED	TS. FUKUSHIMA	16.01.21
			DESIGNED	TS. KUMAZAWA	16.01.21
			DRAWN	TS. KUMAZAWA	16.01.19
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-083466-77-00
HRS	SPECIFICATION SHEET		PART NO.	DF13A-10P-1. 25H (77)	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL536-0309-0-77	△ 1/1